

# QUIK STIK

A two part unfilled epoxy adhesive designed for high speed bonding of metal, ceramics and most plastics. It cures to a tough semi-rigid material and is free flowing in viscosity. It gives a good resistance to water, salt spray, inorganic acids and bases and most organic solvents. It was especially formulated to a 1:1 mix ratio. Cure is normally achieved at room temperature within 20 to 30 minutes, with full cure in 24 hours. An elevated temperature cure schedule can be used to reach final properties quickly.

**FEATURES:**

- Clear color
- 3 to 5 minutes Pot Life, Mass 20 gm
- 80 Hardness Shore-D
- 13,000 cps (est) Viscosity Mixed
- 1.16 Specific Gravity Mixed
- 2,800 psi Tensile Strength, Lap Shear (Al/Al)
- 410 V/mil Dielectric Strength
- (-40 to 130) °C, 130°C = 266°F Temp. Range
- 12 Months Shelf Life from D.o.M. (un-opened)

**MIX RATIO:**

1A:1B by weight of 1A:1B by volume.

**Product Availability:**

| PART No. | DESCRIPTION | SIZE              |
|----------|-------------|-------------------|
| 10-114   | Quik Stik   | (2) 1/2 oz. Tubes |



CoO: USA  
UPC: 010151130969  
HTS: 8204.20.0000  
HTS: 8536.50.9065

**PART No: 10-114**

1. Bring both components to room temperature prior to mixing. Mix 1 part of A to 1 part of B thoroughly.
2. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
3. Clean up uncured resin with suitable organic solvent such as MEK, Acetone or a Chlorinated Solvent.